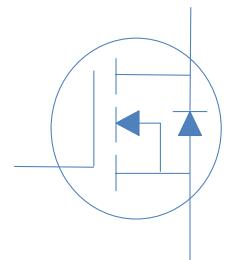
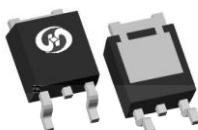


**65V N-Ch Power MOSFET**
**H**

$V_{DS}$	65	V
$R_{DS(on),typ}$	$V_{GS}=10V$	3.8 m
$R_{DS(on),typ}$	$V_{GS}=4.5V$	5.5 m
$I_D$ (Silicon Limited)		101 A

**H**


Part Number	Package	Marking
HGD046NE6AL	TO-252	GD046NE6AL

### Absolute Maximum Ratings at $T_J=25^\circ C$ (unless otherwise specified)

Parameter	Symbol	Conditions	Value	Unit
Continuous Drain Current (Silicon Limited)	$I_D$	$T_C=25^\circ C$	101	A
		$T_C=100^\circ C$	72	
Drain to Source Voltage	$V_{DS}$	-	65	V
Gate to Source Voltage	$V_{GS}$	-	$\pm 20$	V
Pulsed Drain Current	$I_{DM}$	-	340	A
Avalanche Energy, Single Pulse	$E_{AS}$	$L=0.1mH, T_C=25^\circ C$	31	mJ
Power Dissipation	$P_D$	$T_C=25^\circ C$	94	W
Operating and Storage Temperature	$T_J, T_{stg}$	-	-55 to 175	°C

### Absolute Maximum Ratings

Parameter	Symbol	Max	Unit
Thermal Resistance Junction-Ambient	$R_{JA}$	50	°C/W
Thermal Resistance Junction-Case	$R_{JC}$	1.6	°C/W

Drain to Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250 \text{ A}$				
	$V_{GS(\text{th})}$	$V_{GS}=V_{DS}, I_D=250 \text{ A}$			1.0	
						min
Total Gate Charge						
Turn on Delay Time	$t_{d(on)}$			-	10	-
Rise time	$t_r$	$V_{DD}=30V, I_D=20A, V_{GS}=10V,$		-	8	-
Turn off Delay Time	$t_{d(off)}$	$R_G=10 \Omega$		-	34	-
Fall Time	$t_f$			-	10	-
						ns
Reverse Diode Characteristics						
Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_F=30A$		-	0.9	1.2
						V

Fig 1. Typical Output Characteristics

Figure 2. On-Resistance vs. Gate-Source Voltage



Figure 3. On-Resistance vs. Drain Current and Gate Voltage

Figure 4. Normalized On-Resistance vs. Junction Temperature

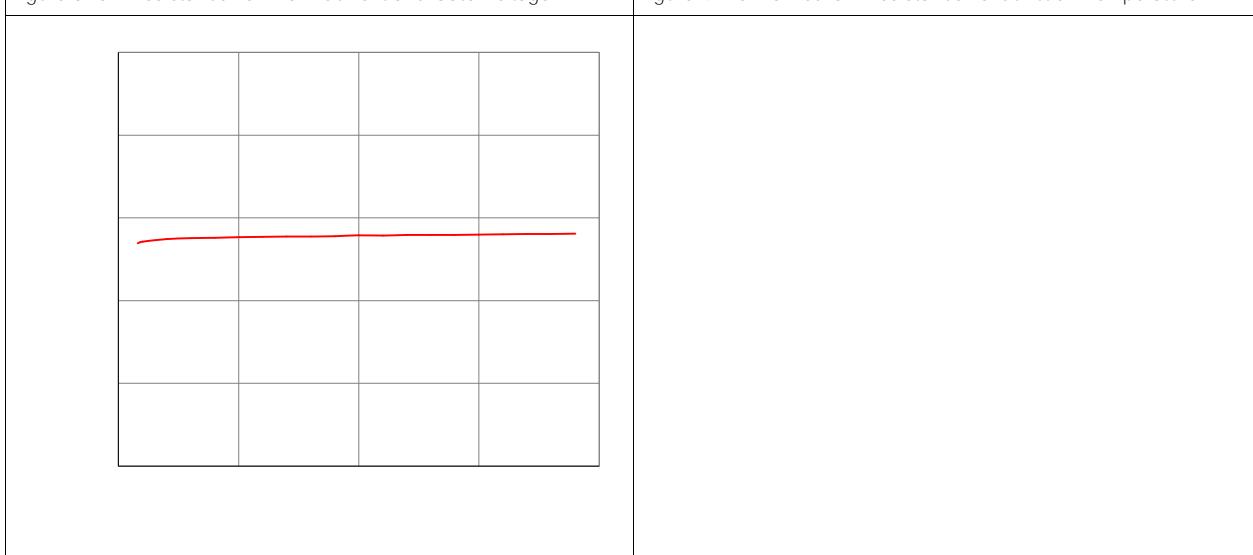


Figure 5. Typical Transfer Characteristics

Figure 6. Typical Source-Drain Diode Forward Voltage

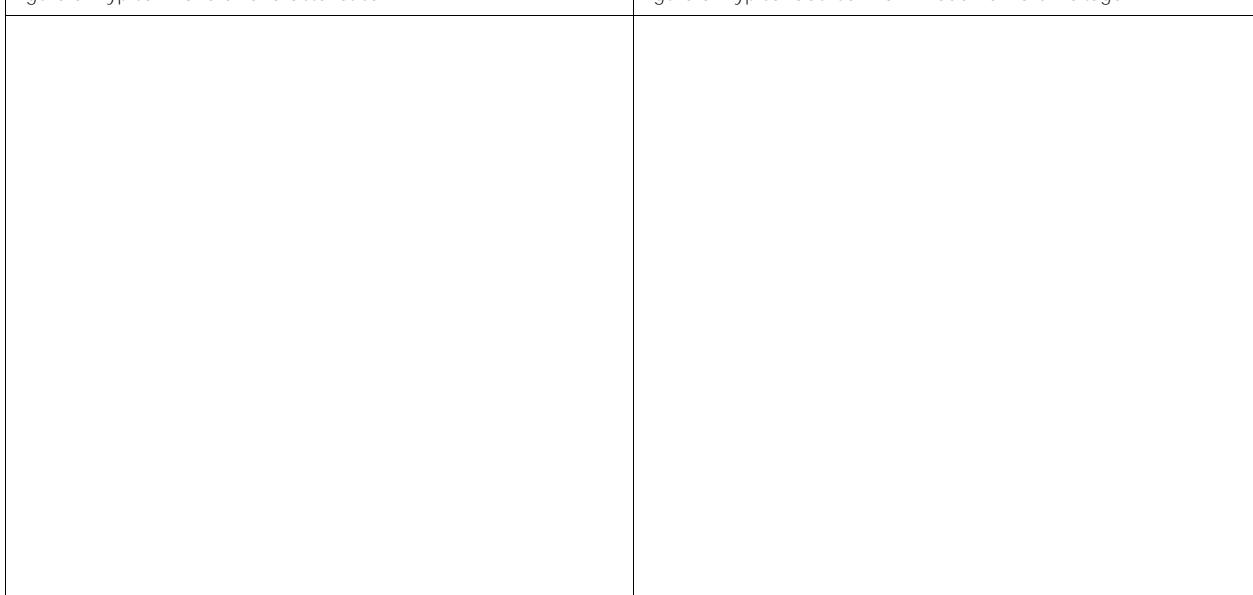


Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

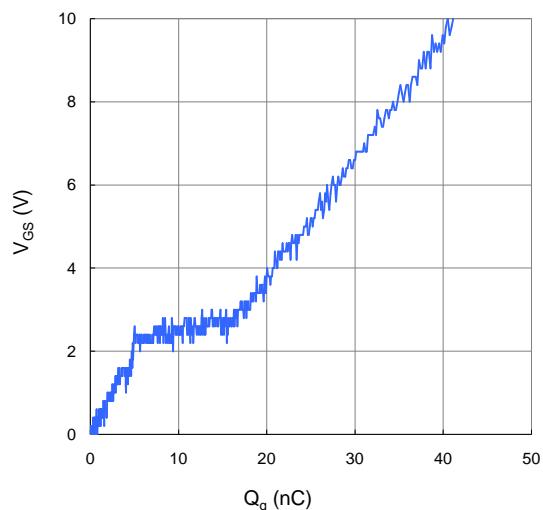


Figure 8. Typical Capacitance vs. Drain-to-Source Voltage

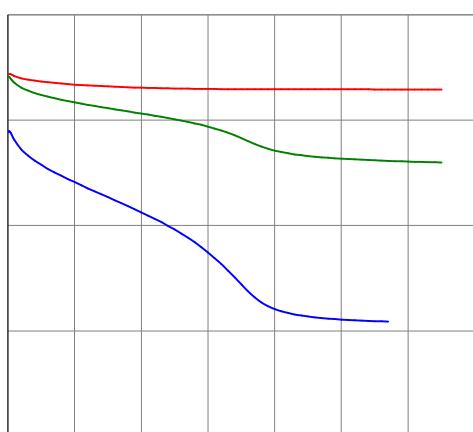
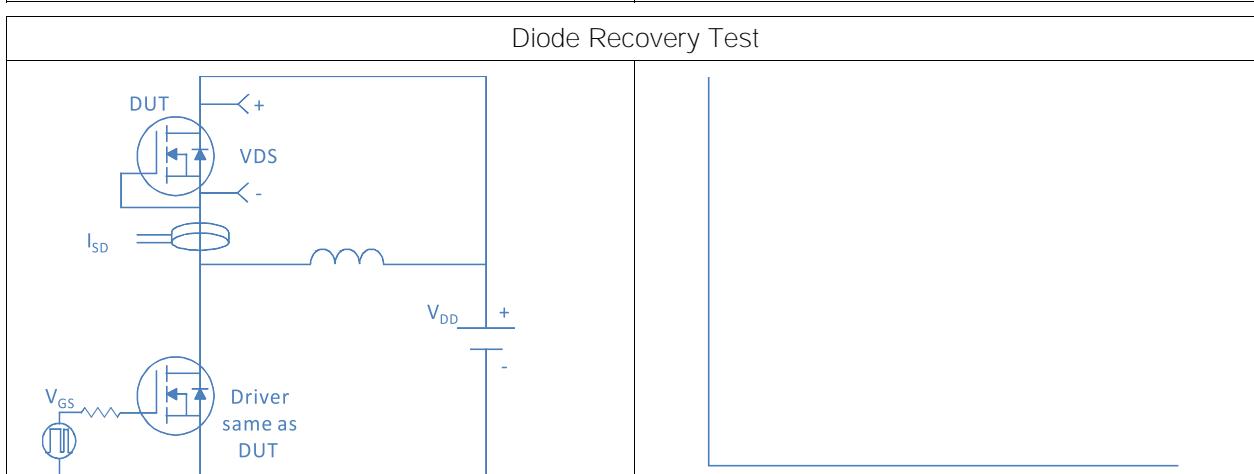
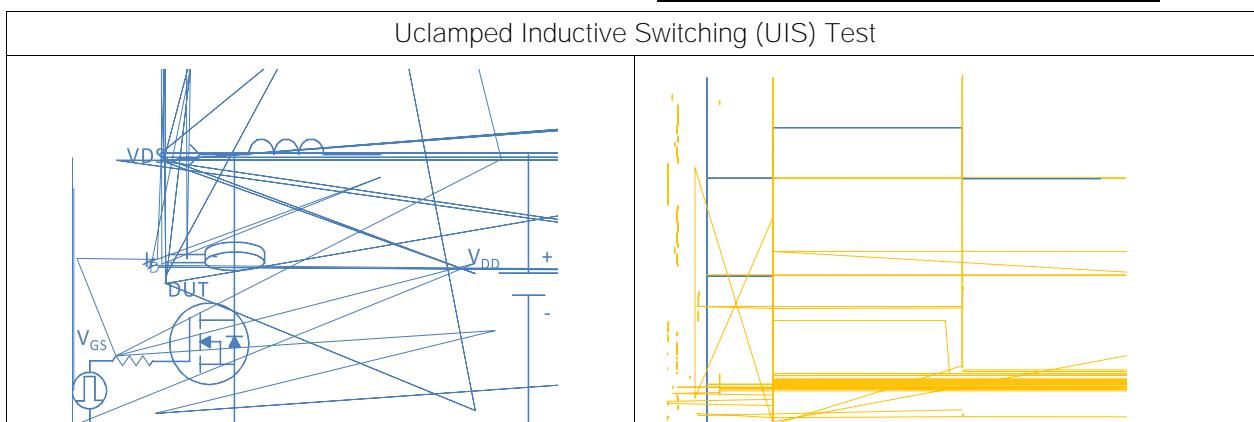
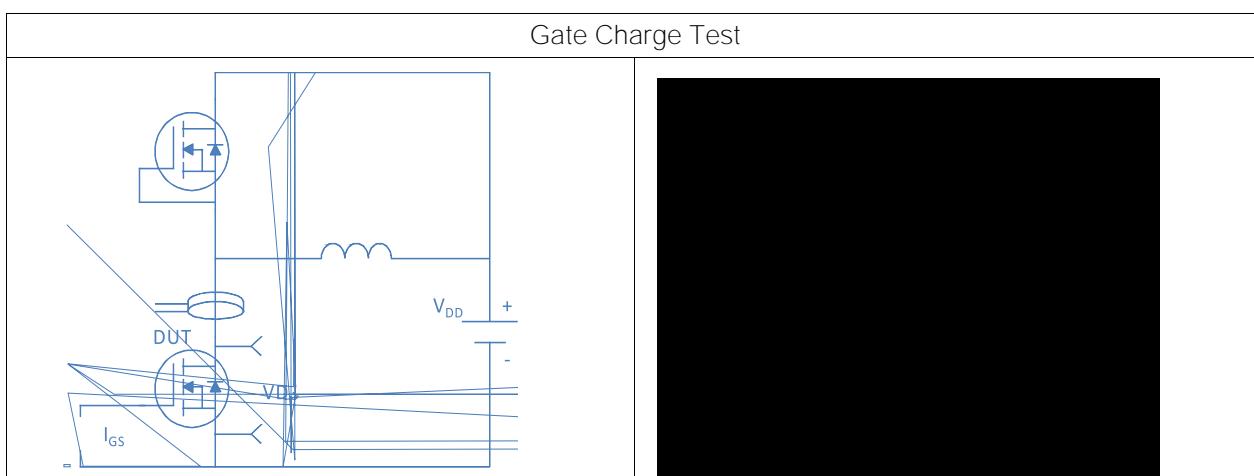
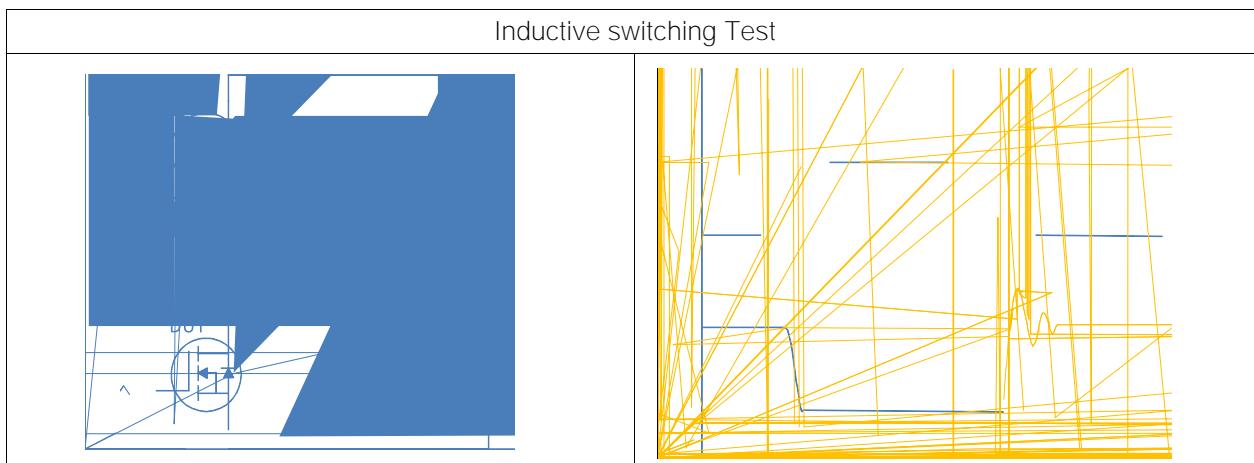


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Ambient



Package Outline